About Organisation

Name of Company:	Qualcomm
Date of Establishment:	1985-01-07
Number of Employees:	47000
Social Media Page Link:	www.qualcomm.com
Website:	www.qualcomm.com
Type of Organization:	MNC (Foreign Origin)
Location of Head office:	USA
Nature of Business:	Core Engineering & Technology

Internship Profile

Job Title: Interim Engineering Intern- SW

Job Description:

Job Area :Engineering - Software
Job Location : Hyderabad / Bangalore / Chennai / Noida
We know our employees' ideas change the world. For more than three decades, we've been a
global leader in mobile technology, continually pushing the boundaries of what's possible.
Working with customers across industries — from automotive to health care, from smart cities to
robotics— we continue to accelerate innovation and unlock new possibilities in a time where
everything is connected. By joining the Qualcomm family, you too can bring the future forward
faster.
As a software engineer, you will design, develop Software for Qualcomm's mobile chipsets
which are based on cutting edge technology.. Qualcomm is looking for energetic, creative and
self-driven engineer to work in
➢ Multimedia Technologies such as Audio and Video codecs, Image Processing,
➢ Wireless Modem Technologies, such as 4G, WiFi, Bluetooth, Self-Organizing Networks.
➢ Platform Level SW, such as, Linux, Android, Windows, Board Support Packages.
➢ IOT Technologies, for Connected Cameras, Smart Assistants, Drones, Virtual Reality,
Augmented Reality.
Campus Grads will be working on following areas:
• Development of real-time embedded software and device drivers

- Mobile SW development for Windows Mobile, Android or Linux
- Good understanding of OS concepts, Data structures, etc
- C/C++ and object oriented design
- Wireless network standards such as CDMA/GSM/UMTS/LTE
- Linux/UNIX, Linux Drivers, Linux Kernel Development
- Protocols such TCP/UDP/IP/SIP/RTP etc
- Multimedia technologies including Audio, Video, Imaging
- Excellent analytical and problem solving skills
- Ability to collaborate and work in teams.
- Good verbal and written communication skill

Opportunities include:
- SW development for Android, Window Mobile based Embedded Platforms
- Multimedia software stack, firmware and driver Development
- Wireless Modem and connectivity Software and Firmware Development
- Communication protocol stack Software Development
- Kernel, BSP and Device Driver Development
- Application SW and UI development.
- SW Architecture for embedded devices based on Android, Windows.
- Design and development based on Object oriented programming.

Education:
Masters, Bachelors: Computer Science Engineering, Communication Engineering, ECE,

Minimum No. of Hires:	2
Expected No. of Hires:	5
Location(s)/Place of Posting/Online:	HYD, Bangalore
Skillset:	CS, ECE
Minimum CGPA:	7.5
Students with backlog eligible:	No

Selection Process

Resume Shortlist:	Yes
Mode of Selection:	Hybrid
Resume shortlisting before test?:	No
Test:	Yes
Mode of Test:	Online
Test duration (minutes):	90
Aptitude/Psycometric:	Yes
Technical:	Yes

Group Discussion:	No
Personal Interview:	Yes
Technical Round:	Yes
HR Round:	Yes
Medical Test:	No

Eligible Academic Programs

Diversity Recruiting:	No
Eligible Years:	Graduating in 2026 (Pre-Final Year Students) - B.Tech / Dual / Master's
Eligible Departments:	B.Tech in Computer Science & Engineering, B.Tech in Electrical Engineering, B.Tech in Electrical Engineering (Power and Automation), B.Tech in Mathematics & Computing, B.Tech and M.Tech in Computer Science & Engineering, B.Tech and M.Tech in Mathematics & Computing

Stipend Details

Stipend (per month) (In INR Per Month):	45,000 INR Per Month
Accommodation:	Yes
Any other perks/ benefits/ components:	Medical Insurance
Provision of PPO based on performance?	Yes
Tentative CTC for PPO select:	29LPA (BTech) 35 LPA (Mtech/Dual Degree) INR Per Annum

Others

Medical Requirements:	No
Other Requirements:	No